

6th & 7th CIES Technology Forum VIRTUAL

March 22 (Tue) – 23 (Wed), 2022

Progress Report

March 23 (Wed) **DAY2**

http://www.cies.tohoku.ac.jp/7th_forum/

Part 1 [Live] 9:00-12:30 (JST)

9:00-9:05	Welcome address	President, Tohoku Univ.	Hideo Ohno (Tohoku Univ.)
	Address	Chairperson, Executive Board, TIA	Tetsuro Higashi (TIA)
	Address	Director-General, Science and Technology Policy Bureau, MEXT	Yoshiyuki Chihara (MEXT)
9:05-9:35	Address	Deputy Director-General, Industrial Science and Technology Policy and Environment Bureau, METI	Tetsuya Tanaka (METI)
	Address	Director-General, 4th Patent Examination Department, JPO	Hitoshi Maeda (JPO)
9:35-10:05	CIES Overview		Tetsuo Endoh (Tohoku Univ.)
10:05-10:25	<i>Industry-academic collaboration</i>	STT-MRAM aimed at developing non-volatile working memory and its manufacturing technologies	Tetsuo Endoh (Tohoku Univ.)
10:25-10:45	<i>Industry-academic collaboration</i>	Supersensitive magnetic sensors using ferromagnetic tunnel junctions	Yasuo Ando (Tohoku Univ.)
10:45-11:05	<i>Industry-academic collaboration</i>	Embedded security technology	Koichi Ito (Tohoku Univ.)
11:05-11:25	<i>JST OPERA</i>	World-leading open innovation platform of fusion technologies bridged IT and transportation system areas	Tetsuo Endoh (Tohoku Univ.)
11:25-11:45	<i>JSPS Core-to-Core (Japan – UK – France)</i>	Creation of international research hub for innovative semiconductor materials and devices	Tetsuo Endoh (Tohoku Univ.)
11:45-12:05	<i>NEDO AIC</i>	Computing Technology using CMOS / Spintronics Hybrid Technology	Tetsuo Endoh (Tohoku Univ.)
12:05-12:25	<i>MEXT Power Electronics</i>	Research and development of integrated power electronics for the realization of a decarbonized society	Yoshikazu Takahashi (Tohoku Univ.)
12:25-12:30	Closing remarks		Tetsuo Endoh (Tohoku Univ.)

Part 2 [Streaming] 17:00-19:55 (JST)

17:00-17:30	CIES Overview		Tetsuo Endoh (Tohoku Univ.)
17:30-17:50	<i>Industry-academic collaboration</i>	STT-MRAM aimed at developing non-volatile working memory and its manufacturing technologies	Tetsuo Endoh (Tohoku Univ.)
17:50-18:10	<i>Industry-academic collaboration</i>	Supersensitive magnetic sensors using ferromagnetic tunnel junctions	Yasuo Ando (Tohoku Univ.)
18:10-18:30	<i>Industry-academic collaboration</i>	Embedded security technology	Koichi Ito (Tohoku Univ.)
18:30-18:50	<i>JST OPERA</i>	World-leading open innovation platform of fusion technologies bridged IT and transportation system areas	Tetsuo Endoh (Tohoku Univ.)
18:50-19:10	<i>JSPS Core-to-Core (Japan – UK – France)</i>	Creation of international research hub for innovative semiconductor materials and devices	Tetsuo Endoh (Tohoku Univ.)
19:10-19:30	<i>NEDO AIC</i>	Computing Technology using CMOS / Spintronics Hybrid Technology	Tetsuo Endoh (Tohoku Univ.)
19:30-19:50	<i>MEXT Power Electronics</i>	Research and development of integrated power electronics for the realization of a decarbonized society	Yoshikazu Takahashi (Tohoku Univ.)
19:50-19:55	Closing remarks		Tetsuo Endoh (Tohoku Univ.)

Organizer: Center for Innovative Integrated Electronic Systems (CIES), Tohoku University

Co-sponsored: Research Institute of Electrical Communication (RIEC), Tohoku University

Sponsors: CAO, MEXT, METI, JPO, JSPS, JST, NEDO, INPIT